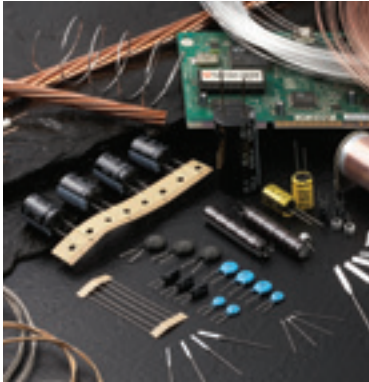


# Lead Wire



Lead wire for interconnecting main electronic components with PCB board in order to activate each component with electrical & physical properties.

**+ Application** Capacitors (Electrolytic, Polymer Solid, Film, Ceramic), Resistor, Diode, Varistor, Jumper, Connector pin.

주요 전자부품과 PCB 기판을 연결함으로써 각 부품의 원활한 기능을 위한 전기적, 물리적 특성을 갖춘 인입선.

**+ 용도** 콘덴서(전해, 고분자, 필름, 세라믹), 저항, 다이오드, 바리스타, 점퍼, 커넥터핀용.

## Wire Specification

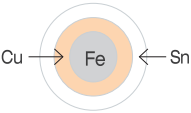
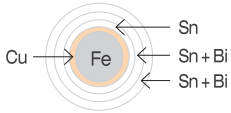
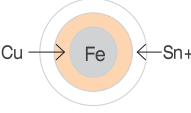
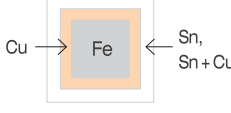
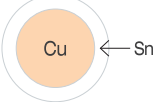
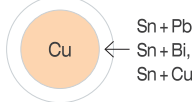
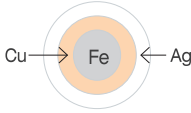
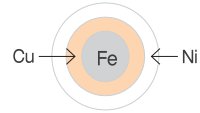
Item	Plating Material	Base Material	Diameter (mm)	Plating Thickness(μm)	Conductivity (%)	Tensile Strength(kgf/mm <sup>2</sup> )	
						Soft	Hard
TPC	Sn 100%	CP	0.26-1.5	Max. 14	15-53	Max. 45	44~62
TCA		Cu	0.26-1.5	Max. 14	Min. 90	Max. 28	Max. 35
TCO		OFC	0.26-1.5	Max. 14	Min. 90	Max. 28	Max. 35
TSBC		SBC*	0.26-1.0	Max. 14	Min. 90	Max. 28	Max. 35
TPC(B)	Sn+Bi	CP	0.26-1.5	Max. 14	15-53	Max. 45	44~62
TCA(B)		Cu	0.26-1.5	Max. 14	Min. 90	Max. 28	Max. 35
TCO(B)		OFC	0.26-1.5	Max. 14	Min. 90	Max. 28	Max. 35
TPC(C)	Sn+Cu	CP	0.26-1.5	Max. 14	15-53	Max. 45	44~62
TCA(C)		Cu	0.26-1.5	Max. 14	Min. 90	Max. 28	Max. 35
TCO(C)		OFC	0.26-1.5	Max. 14	Min. 90	Max. 28	Max. 35
APC	Ag	CP	0.26-0.8	Max. 10	15-53	Max. 45	44~62
ACA		Cu	0.26-0.8	Max. 10	Min. 98	Max. 28	Max. 35
ACO		OFC	0.26-0.8	Max. 10	Min. 98	Max. 28	Max. 35
ASBC		SBC	0.26-0.8	Max. 10	Min. 98	Max. 28	Max. 35
NPC	Ni	CP	0.26-1.0	Max. 10	15-53	Max. 45	44~62
NCA		Cu	0.26-1.0	Max. 10	Min. 90	Max. 28	Max. 35
NCO		OFC	0.26-1.0	Max. 10	Min. 90	Max. 28	Max. 35
CPS	Cu	Fe	0.26-1.5	*	15-53	Max. 45	44~62

※ SBC : Silver Bearing Copper.





※ CPS's plating thickness depends on wire diameter.

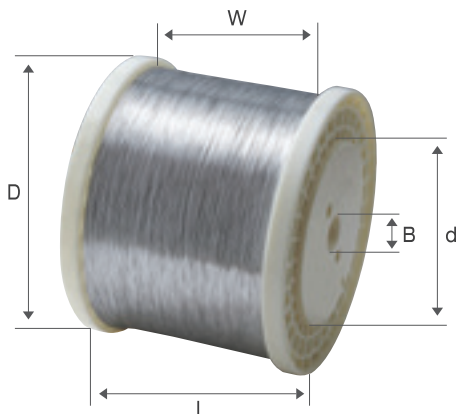
※ Any specification except the above is negotiable.

### Cross Section of Wire

Item	Cross Section	Item	Cross Section
Tin Plated on Copper Covered Steel Wire TPC		Sn+Bi Plated on Copper Covered Steel Wire TPC(B)	
Sn+Cu Plated on Copper Covered Steel Wire TPC(C)		Tin(or Sn+Cu) Plated on Copper Covered Square Steel Wire TPCHFS, TPCHFS(C)	
Tin Plated on Annealed Copper Wire TCA		Sn+Pb(Sn+Bi or Sn+Cu) Plated on Annealed Copper Wire 5TCA, TCA(B), TCA(C)	
Ag Plated on Copper Covered Steel Wire APC		Ni Plated on Copper Covered Steel Wire NPC	

### Packing

Type	A	B	C	D
Material				
	Paper Box	PVC Drum	P.P Drum	Fiber Drum
Dimension (mm)	280(L) X 280(W) X 265(H)	Ø250 X 285(H)	Ø290 X 320(H)	Ø400 X 290(H)
Weight (kg)		13-22		35-50



Bobbin Type	Dimension (mm)					Packing Weight (kg)
	D	d	B	W	L	
D-250	250	160	22	160	200	20
P-30	300	130	32	130	150	30
P-5	160	70	22	90	114	5

※ Any packing requirement except the above is negotiable.

# Hot-dipped Lead Wire



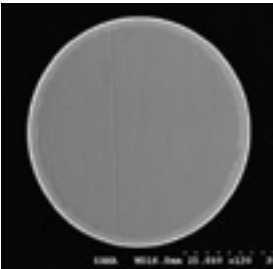
Hot-dipped type lead wire having proved whisker-free solution and heat-resistance properties with tight tolerance of coating thickness on a wire.

**+ Application** High voltage capacitor, Ceramic capacitor and other special usage.

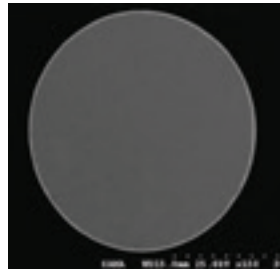
Whisker-free 특성과 함께 강한 내열성을 가진 도금두께가 균일한 용융도금 리드와이어.

**+ 용도** 고전압 콘덴서, 세라믹 콘덴서 및 다양한 부품용.

## Tight Tolerance of Coating Thickness



Base : CP Wire



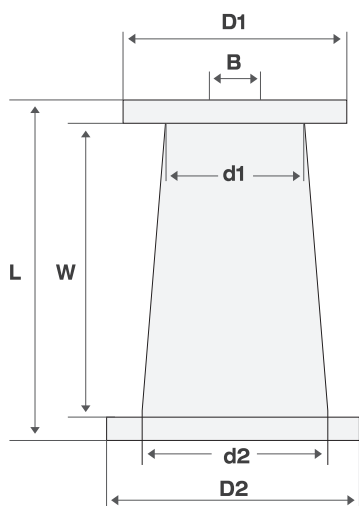
Base : Copper Wire

## Wire Specification

Item	Plating Material	Base Material	Diameter (mm)	Plating Thickness (μm)	Conductivity (%)	Tensile Strength (kgf/mm <sup>2</sup> )	
						Soft	Hard
HPC	Sn	CP	0.4-1.0	8, +3/-2	21-53	Max. 45	44~62
HCA		Cu	0.4-1.0	8, +3/-2	Min. 90	Max. 28	Min. 28
HPC(C)	Sn+Cu	CP	0.4-1.0	8, +3/-2	21-53	Max. 45	44~62
HCA(C)		Cu	0.4-1.0	8, +3/-2	Min. 90	Max. 28	Min. 28

※ Any specification except the above is negotiable.

## Packing



Bobbin Type	Dimension (mm)							Packing Weight (kg)
	D1	D2	d1	d2	B	W	L	
PT-25	215	230	110	130	32	250	280	25

※ Any packing requirement except the above is negotiable.

# Aluminum Wire



High purity Aluminum wire with over 99.90% purity level.

**+ Application** Electrolytic capacitor, Polymer solid capacitor, Rivet for high-voltage capacitor, Film deposition, Accessories, Flowering.

전해콘덴서 및 기타 부품용 고순도 Al wire.

**+ 용도** 전해콘덴서, 고분자 콘덴서, 고압콘덴서용 리벳, 필름 증착용, 액세서리, 화훼용.

## Aluminum Wire for Lead Tab

### Chemical Composition



Purity (%)	Si	Fe	Cu	Mn	Cr	Zn	Ti	Al
99.99	Max. 0.005	Max. 0.005	Max. 0.005	-	-	-	-	99.99 over
99.92	Max. 0.05	Max. 0.07	Max. 0.01	Max. 0.01	-	-	Max. 0.01	99.92 over
99.90	Max. 0.05	Max. 0.07	Max. 0.01	Max. 0.01	-	-	Max. 0.01	99.90 over

### Wire Specification

Item Diameter (mm)	99.99%		99.92%		99.90%	
	Tensile Strength (kgf/mm <sup>2</sup> )	Conductivity (%)	Tensile Strength (kgf/mm <sup>2</sup> )	Conductivity (%)	Tensile Strength (kgf/mm <sup>2</sup> )	Conductivity (%)
0.6-1.5	Min. 10	Min. 63	16-22	Min. 61	16-22	Min. 61
1.9-2.5			14-19		14-19	

※ Any specification except the above is negotiable.

## Packing

Type	A		B
Wire Diameter (mm)	0.65-1.5	1.6-2.5	0.65-2.5
Material			
	Paper Box		Fiber Drum
Dimension (mm)	400(L) X 410(W) X 320(H)		∅430 X 580(H)
Weight (kg)	10 X 3EA=30	20 X 1EA=20	50 X 1EA=50
	15 X 2EA=30	10 X 2EA=20	

※ Any packing requirement except the above is negotiable.